




## Retraction Note to: Effect of grain size on the interface structure and shear behavior of lead-free solder joints

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The authors have retracted this article because they have discovered errors which have not been fully accounted for in their measurements.

The authors Zhai Xinmeng, Chen Yue, Li Yuefeng, Zou Jun, Shi Mingming, Qian Qi and Zhang Cheng

agree to this retraction. The authors Yang Bobo and Yang Jie have not responded to any correspondence from the Publisher about this retraction.

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